

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20220127001.1

Qualification of new Fab site (FFAB) using qualified Process Technology, Die Revision, Datasheet update and additional Assembly site/BOM options for select devices

Change Notification / Sample Request

Date: January 31, 2022 **To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's previous announcement to close our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

PCN Team SC Business Services

20220127001.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE INA126UA

CUSTOMER PART NUMBER

null

Technical details of this Product Change follow on the next page(s).

PCN Number: 2022		2012	27001.1		PCN Date:		e:	January 31, 2022	
Title: Qualification of new Datasheet update								nnology, Die Revision, select devices	
Customer	Contact:		<u>PCN</u>	l Manager	Dept: Quality Serv		Quality Services		
Proposed 1 st Ship Date:			Apr	30, 2022	Estimated Sample Availability:		•	Date provided at sample request.	
Change Type:									
	nbly Site			Assembly Process Ass		Ass	embly Materials		
□ Design □	n		\boxtimes	Electrical Spec	ification			Med	chanical Specification
Test S	Site		\boxtimes	□ Packing/Shipping/Labeling		ng		Test Process	
Wafer Bump Site			Wafer Bump Material				Wafer Bump Process		
		\boxtimes	Wafer Fab Materials			\boxtimes	Wa	fer Fab Process	
			Part number c	hange					
PCN Details									

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (FFAB, BICOM3) and assembly site/BOM options (MLA) for selected devices as listed below in the product affected section.

С	urrent Fab Site	9	Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	JIBB	150 mm	FFAB	BICOM3	200 mm

The die was also changed as a result of the process change.

Construction differences are noted below:

Group 1 Devices:

	ASESH	TI Malaysia	
Die thickness (um)	203	191	
Mount compound	EY1000063	4147858	
Mold compound	EN2000631	4226323	
Wire type	Au	Cu	
Leadframe finish	NiPdAuAg	NiPdAu	
Marking Differences	A26 YMLL YM = YEAR MONTH DATE CODE LL = ASSEMBLY LOT CODE O = PIN 1 INDICATOR (MARK)	BB YM A26 O (CAV) BB = BB LETTERS YM = YEAR MONTH DATE CODE O = PIN 1 INDICATOR (DIMPLE) CAV = CAVITY NUMBER	

Group 2 Devices:

	Current - MLA	New - MLA
Mold Compound	4209640	4226323
Mount Compound	4205846	4147858
Bond Wire Composition/Diameter	Au/1.15 mils	Cu/1.0 mil
MSL	MSL3	MSL2

The datasheet will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The link to the revised datasheet is available in the table below.



INA126, INA2126

SBOS062C - SEPTEMBER 2000 - REVISED JANUARY 2022

PCN# 20220127001.1

Cł	nanges from Revision B (December 2015) to Revision C (December 2021) Page
	Updated the numbering format for tables, figures, and cross-references throughout the document
	Added dual supply specification to Absolute Maximum Ratings
	Deleted redundant operating temperature and input common mode voltage specifications in <i>Recommended</i>
	Operating Conditions
	Added dual supply and specified temperature specifications in Recommended Operating Conditions
	Added proper signs for PSRR and input bias current specifications in Electrical Characteristics
	Deleted V _O = 0 V test condition of common-mode voltage specification in <i>Electrical Characteristics</i>
	Changed common-mode voltage specification from ±11.25 V minimum, to –11.25 V minimum and 11.25 V
	maximum, in Electrical Characteristics
	Changed minimum CMRR specification for INA126U/E, INA2126E from 83 dB to 80 dB in <i>Electrical</i>
	Characteristics
	Added typical input bias current specification of ±10 nA for INA126PA/UA/EA and INA2126PA/UA/EA in
	Electrical Characteristics
	Changed current noise specifications in <i>Electrical Characteristics</i> from 60 fA/ $\sqrt{\text{Hz}}$ to 160 fA/ $\sqrt{\text{Hz}}$ for f = 1 kHz,
	and from 2 pApp to 7.3 pApp for f = 0.1 Hz to 10 Hz
	Changed test condition for short-circuit current specification in <i>Electrical Characteristics</i> from "Short circuit to
	ground" to "Continuous to V _S / 2" for clarity
	Changed short-circuit current specification in Electrical Characteristics from +10/-5 mA to ±5 mA
	Deleted redundant voltage range, operating temperature range, and specification temperature range
	specifications from Electrical Characteristics
	Changed Figures 6-7, 6-10, 6-13, 6-14, 6-15, 6-16, 6-17
	Added Figure 6-11

Product Family	Current Datasheet Number	New Datasheet Number	Link to full datasheet
INA126, INA2126	SBOS062B	SBOS062C	http://www.ti.com/product/INA126

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
No Change	No Change	No Change	$oxed{oxed}$ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising

Die Rev:

Current New

Die Rev [2P]	Die Rev [2P]
D	A

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASESH	ASH	CHN	Shanghai
TI Malaysia	MLA	MYS	Kuala Lumpur

Sample product shipping label (not actual product label)

TEXAS
INSTRUMENTS
MADE IN: Malaysia
2DC: 20:

ZDC: 2Q; MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: 1750 LBL: 5A (L)T0:1750

(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483812

(P) (2P) REV: (V) 0033317 (20L) 630. SHE (21L) 660. USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

Group 1 - FFAB/Process migration, Die Rev, Datasheet & MLA A/T Site + BOM updates:						
INA126E/250	INA126E/2K5	INA126EA/250	INA126EA/2K5G4			
INA126E/250G4	INA126E/2K5G4	INA126EA/2K5				

Group 2 - FFAB/Process migration, Die Rev, Datasheet and BOM updates:						
INA126U	INA126U/2K5G4	INA126UA/2K5	INA126UAG4			
INA126U/2K5	INA126UA					
		1				

Qualification Report

Approve Date 30-Nov-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Data	Displayed as. Hallis		ar sample size / rotal	lanea	
Туре	Test Name / Condition	Duration	Qual Device: INA126U	QBS Process Reference: INA828ID	QBS Process Reference: OPA202ID	QBS Package Reference: INA849D
HTOL	Life Test, 100C ^A	300 Hours	-	-	-	1/77/0
HTOL	Life Test, 150C	300 Hours	1/77/0	3/231/0	3/231/0	-
HBM	ESD - HBM	500 V	1/3/0	1/3/0	3/9/0	1/3/0
HBM	ESD - HBM	1000 V	1/3/0	1/3/0	3/9/0	1/3/0
НВМ	ESD - HBM	2000 V	1/3/0	1/3/0	3/9/0	1/3/0
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	3/9/0	1/3/0
CDM	ESD - CDM	1500 V	1/3/0	-	-	1/3/0
CDM	ESD - CDM	750 V	1/3/0	-	3/9/0	1/3/0
LU	Latch-up	Per JESD78	1/6/0	1/6/0	1/6/0	1/6/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	3/Pass	1/30/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	3/231/0	3/231/0
LU	Latch-up	Per JESD78	1/6/0	1/6/0	1/6/0	1/6/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	3/231/0	3/231/0
тнв	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0

⁻ QBS: Qual By Similarity

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

Qualification Report

Approve Date 13-Jan-2022

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: INA126E	QBS Product Reference: <u>INA126U</u>	QBS Process Reference: <u>INA828ID</u>	QBS Package Reference: <u>OPA2145IDGK</u>	QBS Package Reference: <u>OPA2205ADGK</u>	QBS Package Reference: <u>OPA2206ADGK</u>
HTOL	Life Test, 150C	300 Hours	-	1/77/0	3/231/0	-	1/77/0	2/154/0
ELFR	Early Life Failure Rate, 150C	24 Hours	-	-	-	-	1/800/0	2/2400/0
НВМ	ESD - HBM	2000V	-	1/3/0	1/3/0	-	1/3/0	1/3/0
CDM	ESD - CDM	1000V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	2/6/0
LU	Latch-up	Per JESD78	-	1/6/0	1/6/0	-	1/6/0	1/6/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	3/90/0	1/30/0	1/30/0	1/30/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	1/77/0	2/154/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	-	1/77/0	2/154/0
LI	Lead Pull	Lead Pull	-	-	-	-	1/6/0	2/12/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	1/77/0	3/231/0	1/77/0	1/77/0	2/154/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	2/154/0

⁻ QBS: Qual By Similarity

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

⁻ Qual Device INA126U is qualified at L2, 260C

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

A Tj of device at 150C

⁻ Qual Device INA126E is qualified at L2, 260C

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com

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